



US00D693319S

(12) **United States Design Patent**  
**Osada**

(10) **Patent No.:** **US D693,319 S**

(45) **Date of Patent:** **\*\* Nov. 12, 2013**

(54) **HOLDING PAD FOR TRANSFERRING A  
WAFER**

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(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/425,303**

(22) Filed: **Jun. 21, 2012**

(30) **Foreign Application Priority Data**

Dec. 22, 2011 (JP) ..... D2011-029877

(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/182; 118/500, 724, 725, 728, 729;  
414/217, 222.01, 416.03, 935, 936,  
414/937, 938, 939, 940, 941  
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a holding pad for transferring a wafer, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a holding pad for transferring a wafer showing my new design.

FIG. 2 is a rear view of the holding pad for transferring a wafer of FIG. 1.

FIG. 3 is a top plan view of the holding pad for transferring a wafer of FIG. 1.

FIG. 4 is a bottom plan view of the holding pad for transferring a wafer of FIG. 1.

FIG. 5 is a right side view of the holding pad for transferring a wafer of FIG. 1.

FIG. 6 is a left side view of the holding pad for transferring a wafer of FIG. 1.

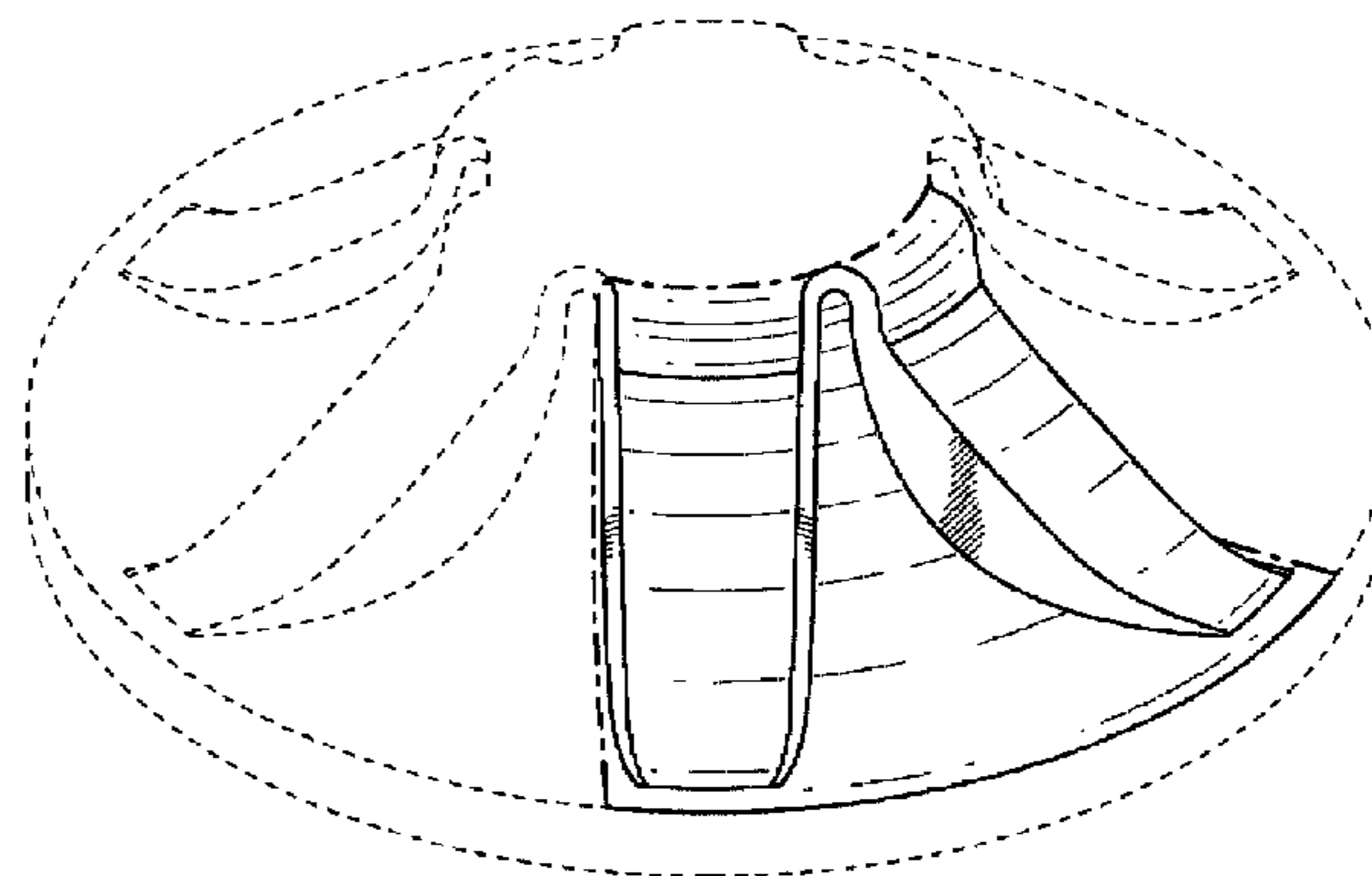
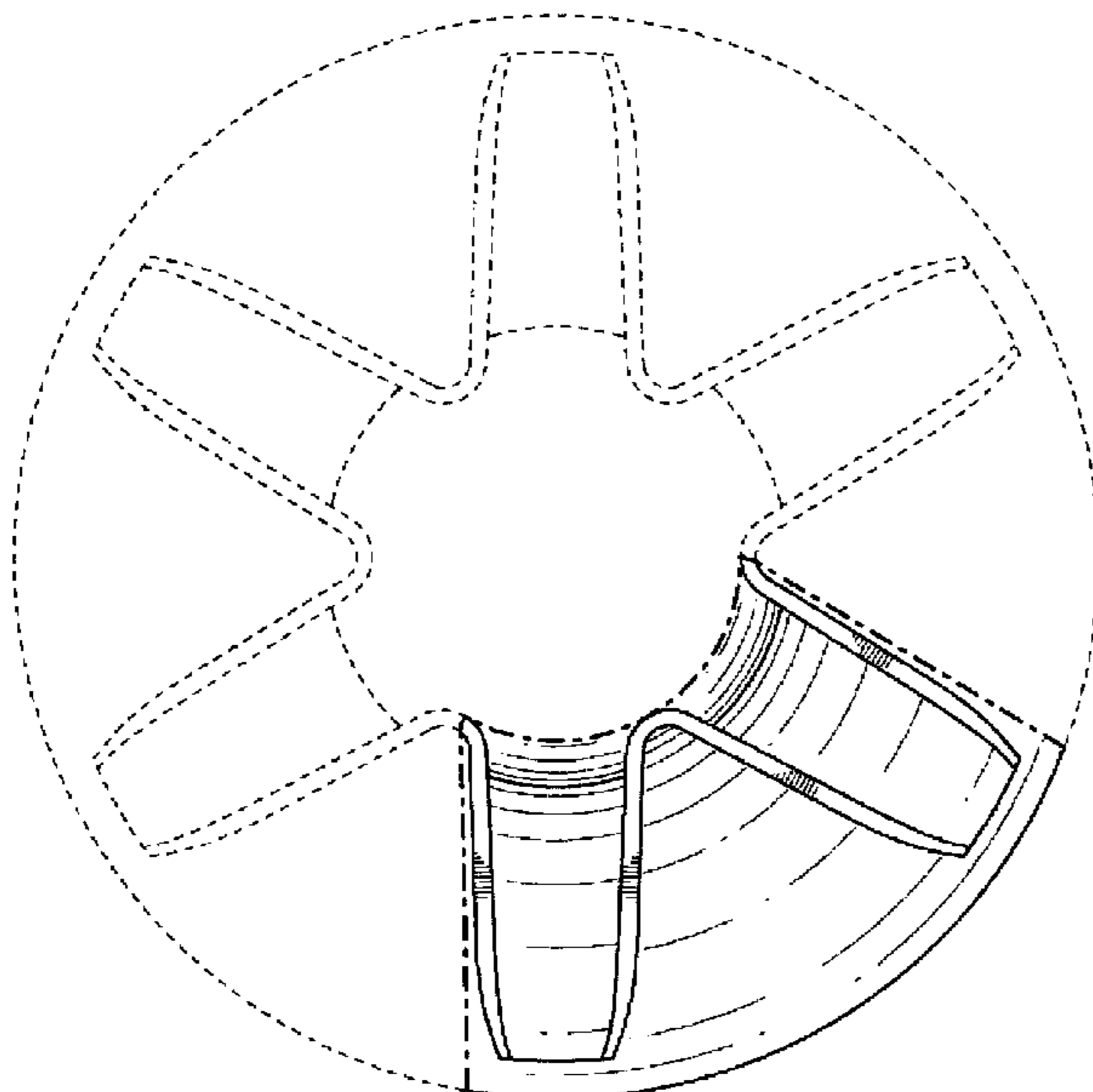
FIG. 7 is a perspective view of the holding pad for transferring a wafer of FIG. 1; and,

FIG. 8 is another front view of the holding pad for transferring a wafer of FIG. 1 shown a used condition.

The features shown in broken lines depict environmental subject matter only and form no part of the claimed design.

The dashed-dot-dashed lines define the boundary lines of the claimed design.

**1 Claim, 8 Drawing Sheets**



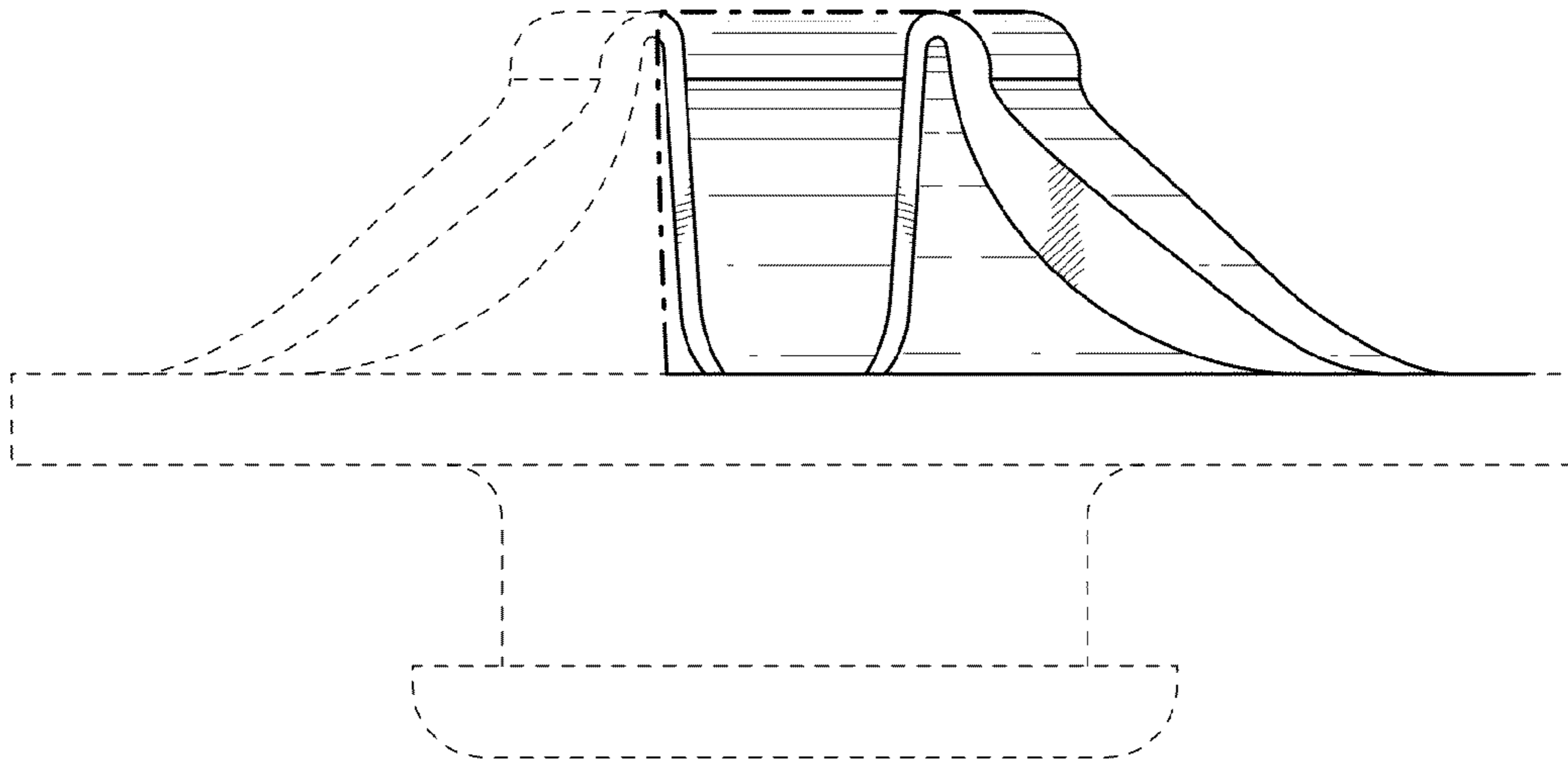


FIG. 1

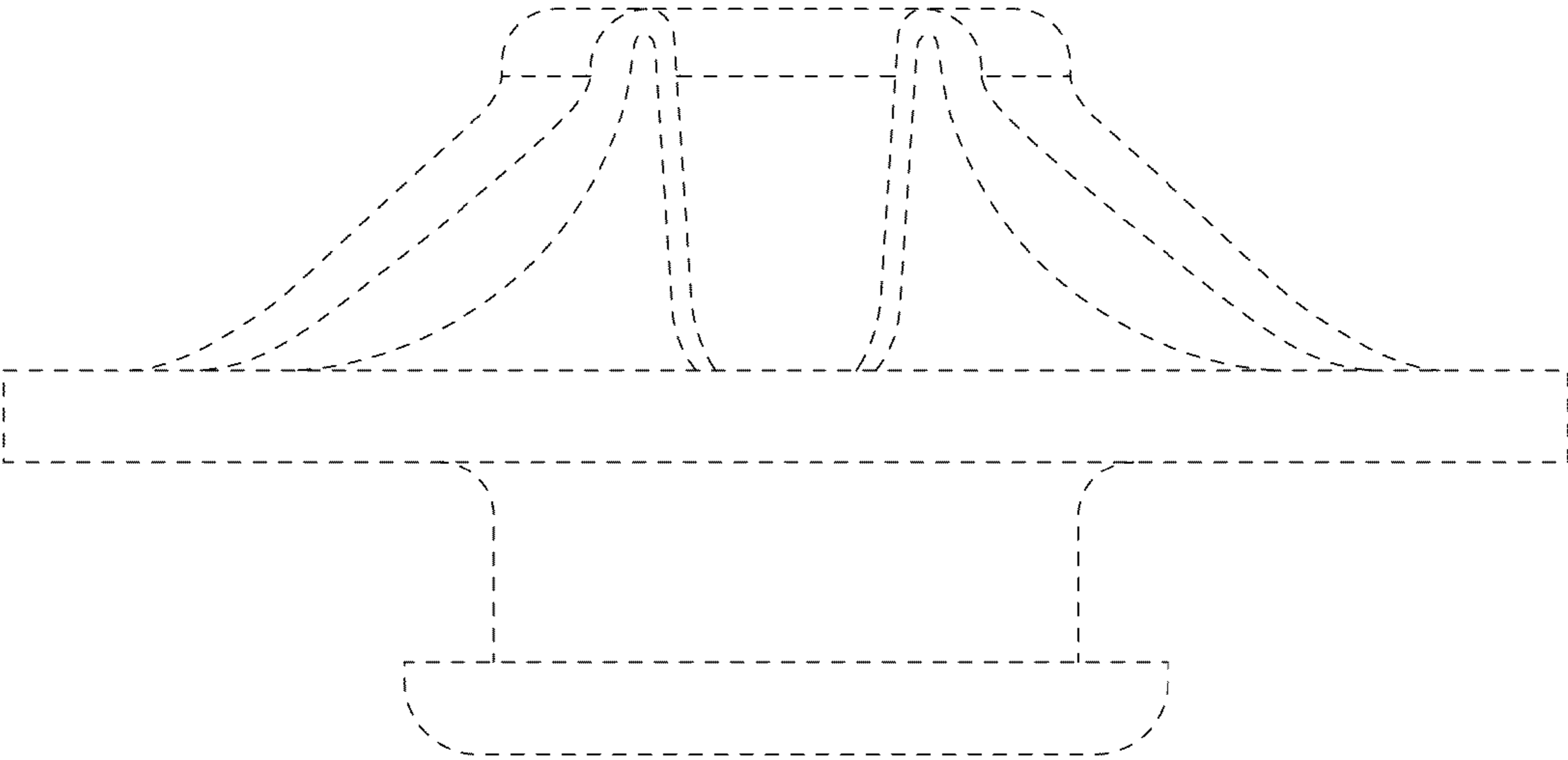


FIG 2

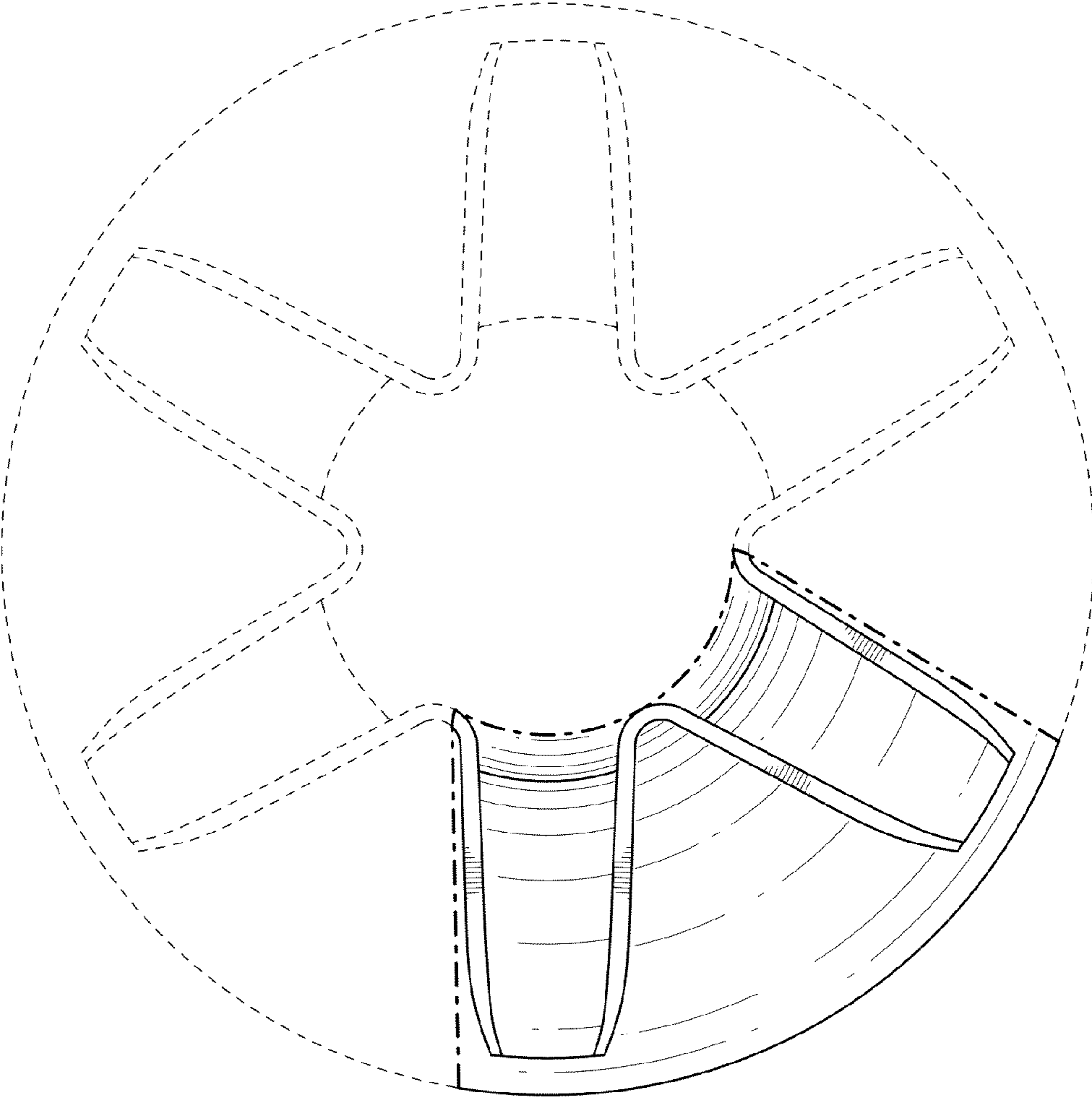


FIG. 3

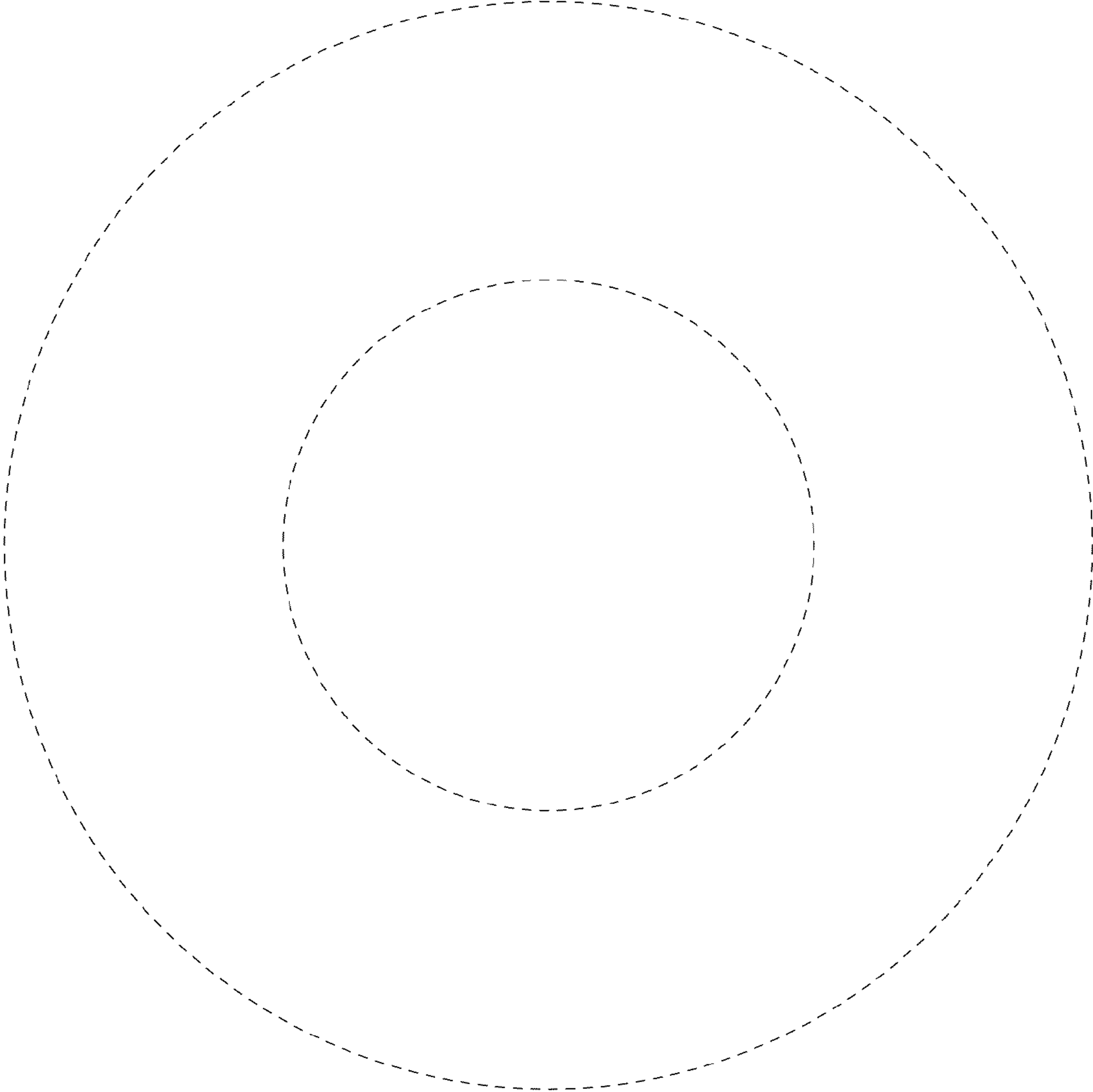


FIG. 4

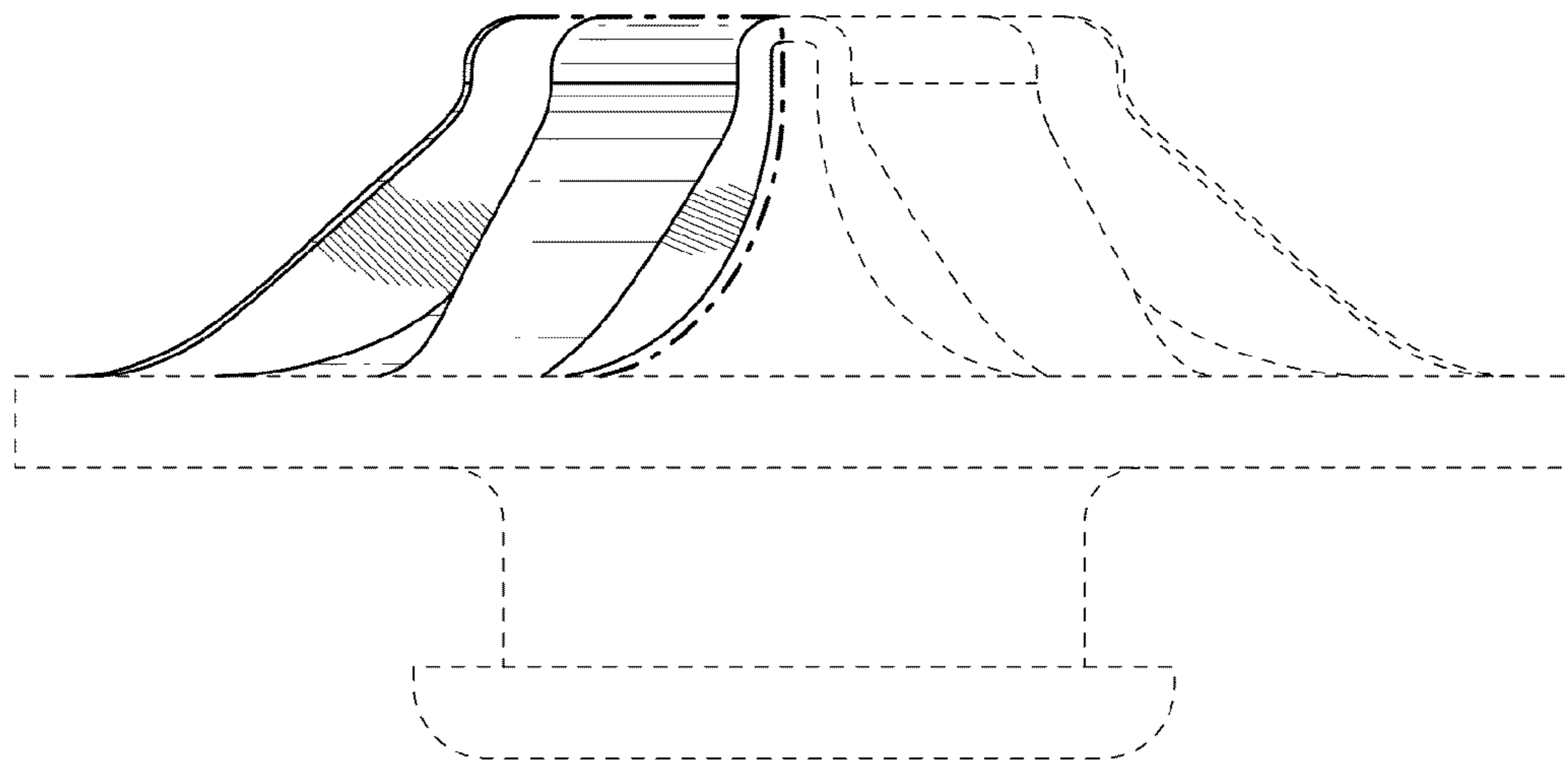


FIG. 5

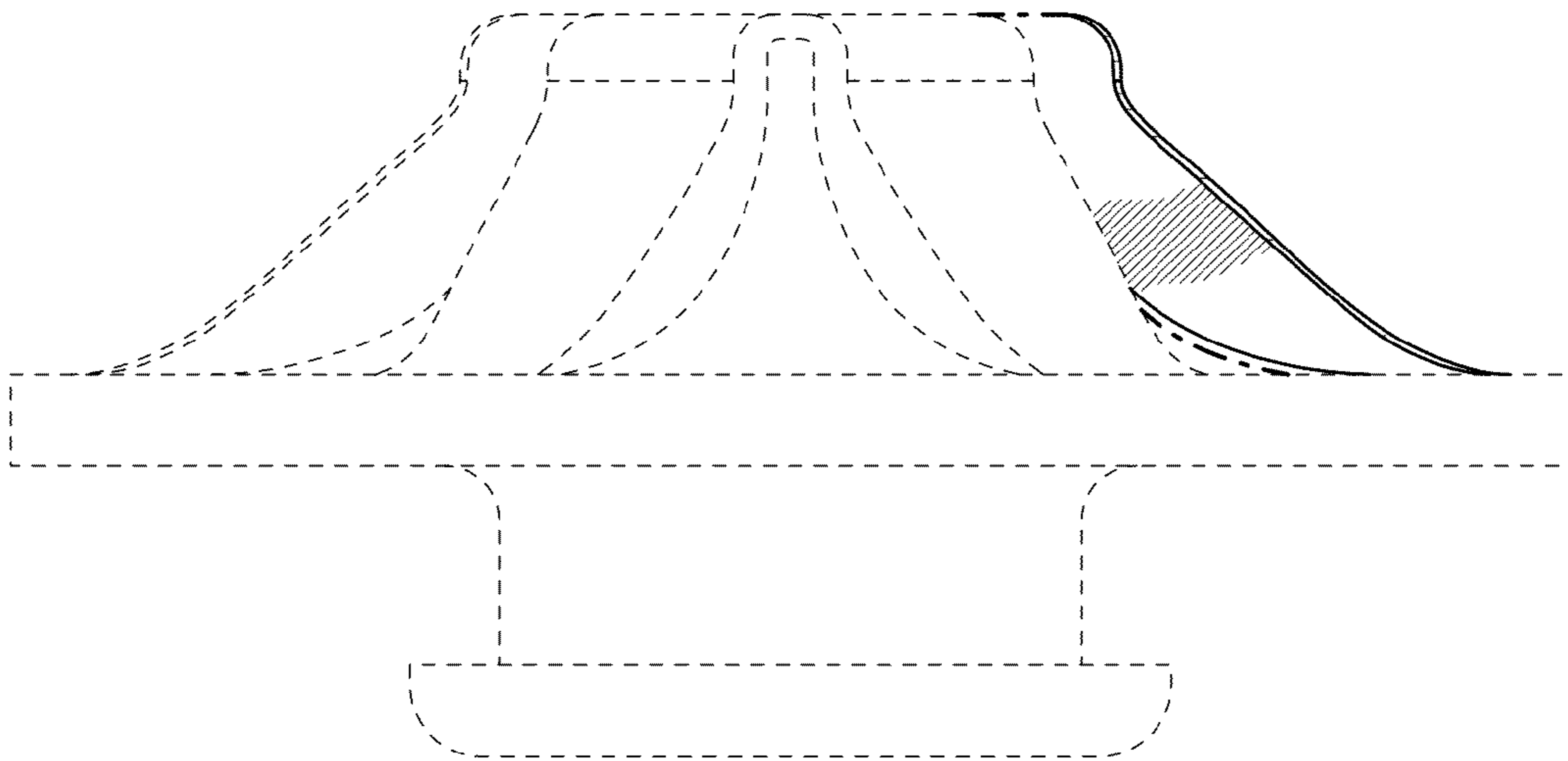


FIG. 6

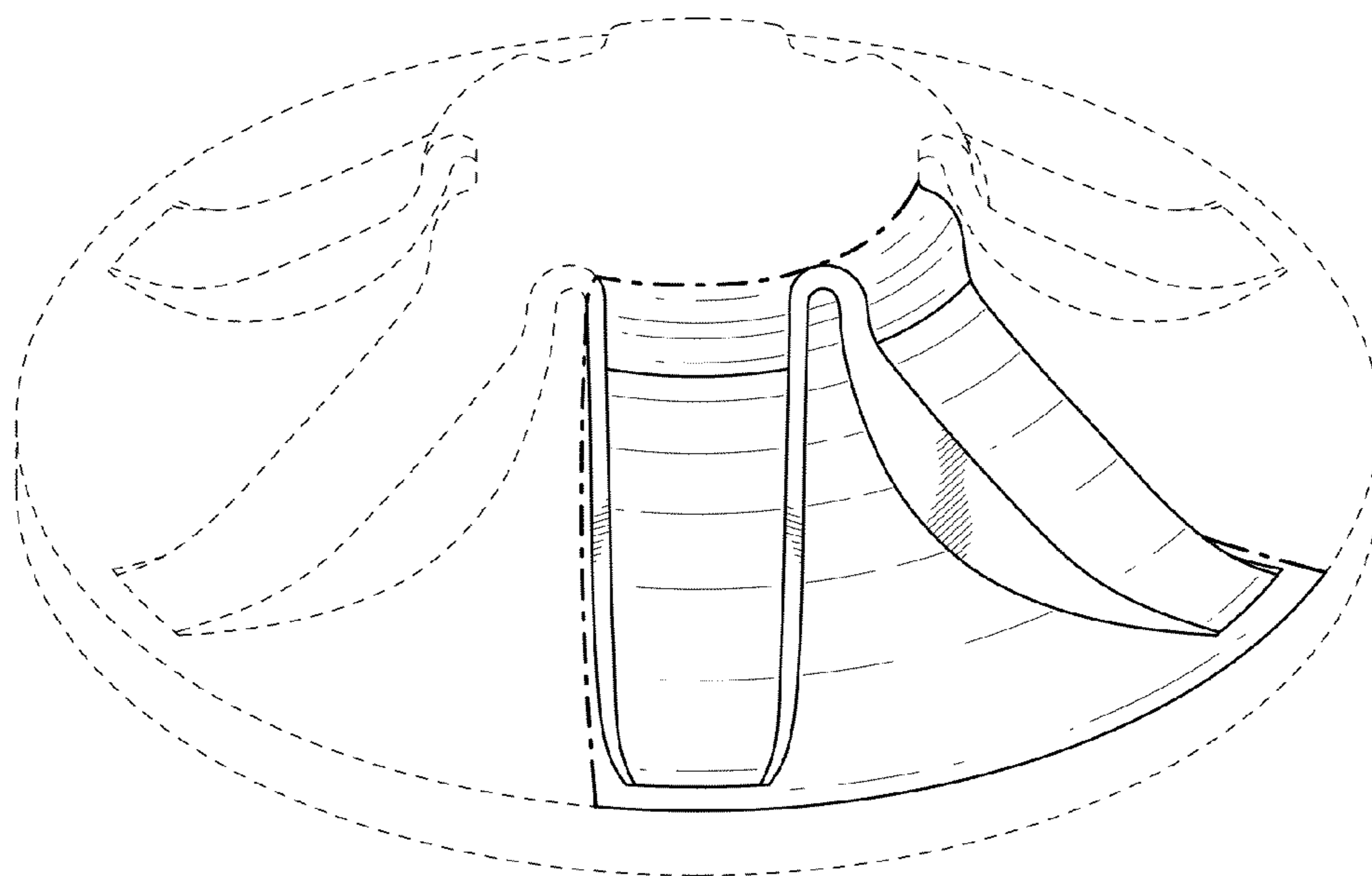


FIG. 7



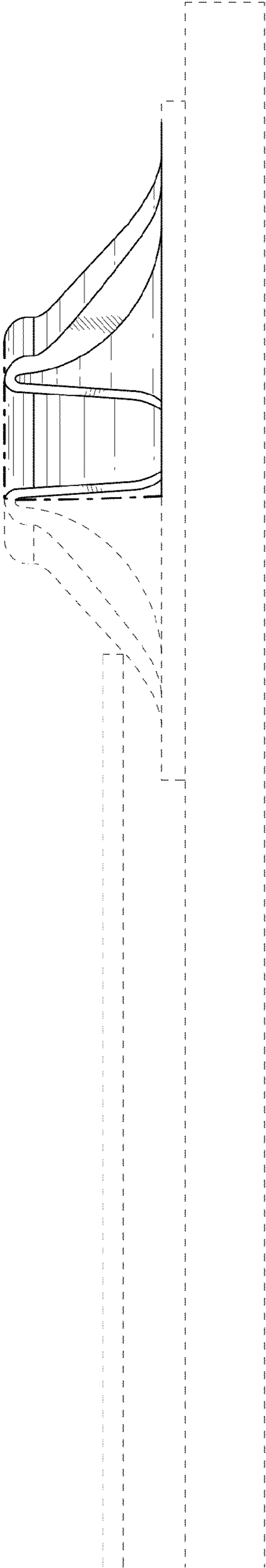


FIG. 8